

# *in situ* AC Impedance Measurement in c-Si PV Modules during Rapid Thermal Cycling Test

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## Introduction & Procedures

### Motivation & Background

**FREA: Fukushima Renewable Energy, AIST**

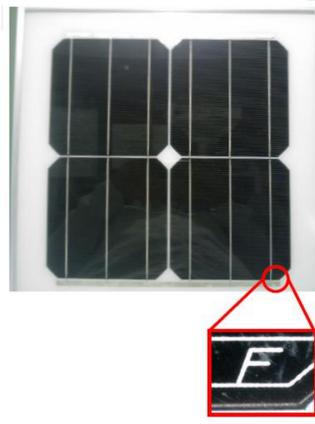
Aim: High Efficiency / Low Cost c-Si PV Cells & Modules  
Thin Wafer PV Cells, Light Weight PV Modules...

Our Task: Thin Wafer PV Cells + Ribbon with Opt. Properties  
-> Reliable / Durable Interconnected PV Modules

To Confirm the Reliability of Soldering Interconnection on these New Designed PV Modules,

- Higher Stress than Conventional Thermal Cycling  
-40 °C/85 °C → -60 °C/100 °C  
Thermal Cycling → Rapid Thermal Cycling  
200 cycles → 3,000 cycles +
- *in situ* Detection of Failures during Testing  
*in situ* AC Impedance Spectroscopy

### Thin Wafer PV Cells / Light Weight Glass → "FREA PV Module"



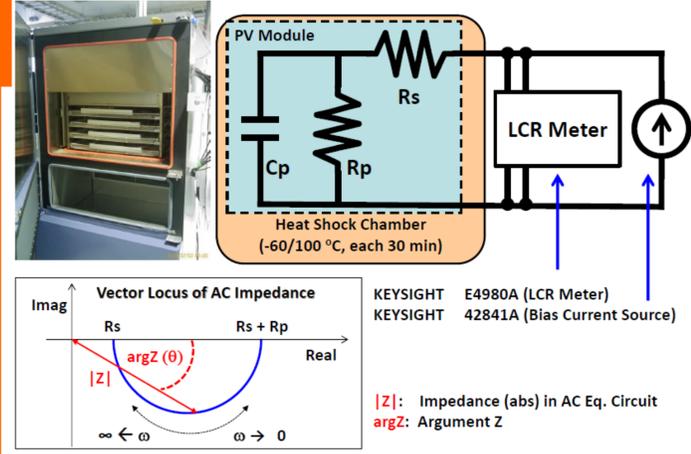
### Tested PV Mini-Module

Thin Wafer PV Cells  
Mfg. in FREA Lab.  
100 μm Thickness  
n-type c-Si / p-doped

Chemical Strengthen Glass  
0.8 mm Thickness

Interconnection  
Cu-Ribbon (1.3 mm)  
by Soldering  
with J-Box & Cables

### Experimental Setup & AC Equivalent Circuit of PV Module



## Summary

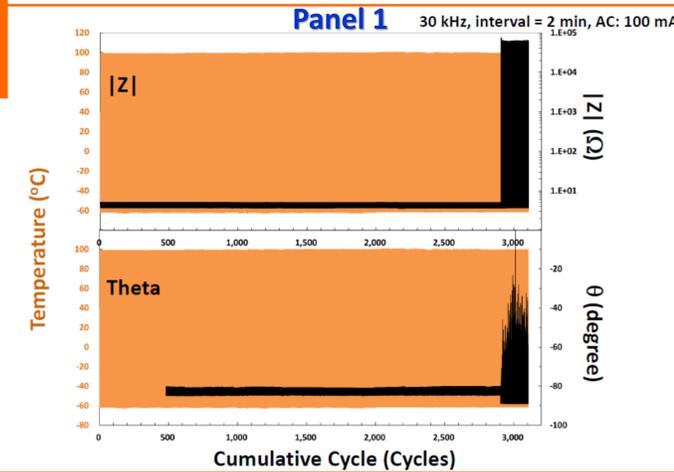
We previously reported that the "spike-like" elevation of whole impedance was observed, which was calculated by the measurement of  $I_{AC}$  and  $V_{AC}$ , prior to the occurrence of interconnection failure during Rapid Thermal Cycling (RTC) test. In this study, the AC impedance parameters ( $|Z|$  and  $\theta$ ) were continuously measured during this testing.

Then, we obtained the results as follows;

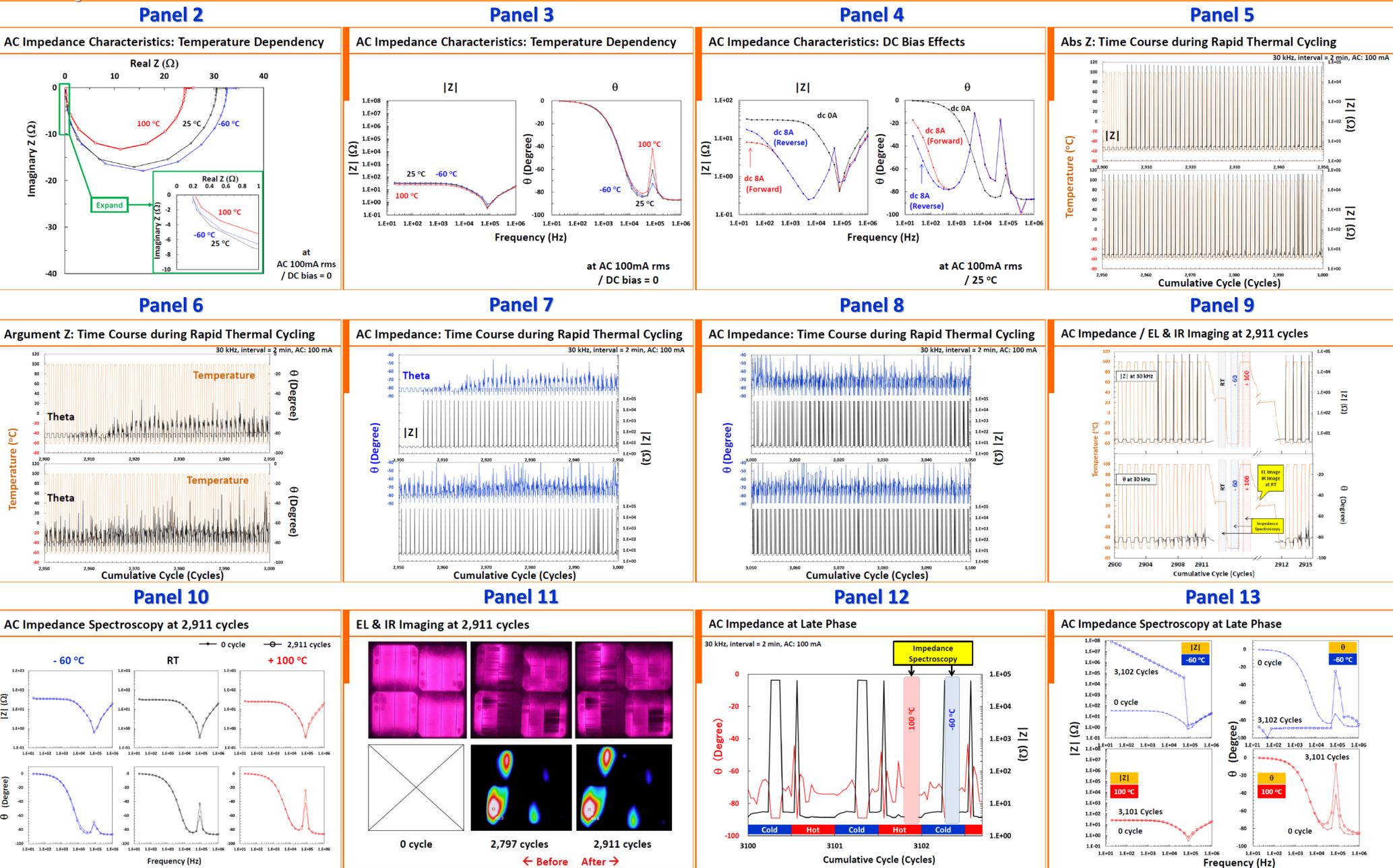
- The logarithmical impedance-elevation identified by  $|Z|$  elevation was observed at ca. 3,000 cycles of RTC (**Panel 1**). Interestingly, the increasing of  $|Z|$  consistently accompanied with  $\theta$  decreasing.
- These level-changes of  $|Z|$  and  $\theta$  were observed in the temperature elevation phase, and also in the low temperature phase after the PV modules were sufficiently adapted at low temperature (**Panel 5-8**).
- When the PV module was completely adapted to any temperature just after these phenomena were happened, the level-changes of AC parameters were not detected at all (**Panel 9-10**). Simultaneously, any alterations of EL and IR images were not confirmed at room temperature (**Panel 11**).
- From the AC impedance spectroscopy (20 Hz ~ 50 kHz) during the  $|Z|$  elevating period (at -60 °C), it is revealed that the levels of  $|Z|$  and  $\theta$  were  $>10^4 \Omega$  and almost -90°, respectively (**Panel 12-13**).

These results suggest that the soldering failure in PV modules (including the disconnection in junction box) can be observed when the RTC testing was conducted for prolonged cycles (ca. 3,000 cycles), and that this failure can be detected only during the RTC testing, as a complete detachment between electrical junctions, by the continuous *in situ* AC impedance measurement.

### AC Impedance: Time Course during Rapid Thermal Cycling



## Experimental Results



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